

Amendments to the Claims:

The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-14. (Cancelled)

15. (Currently Amendment) A semiconductor device, comprising:

an embedded insulation layer formed in a semiconductor substrate;

a plurality of power semiconductor elements formed on said semiconductor substrate;

a trench isolating between said plurality of power semiconductor elements formed on said semiconductor substrate on said embedded insulation layer,

whereby said plurality of semiconductor element are individually isolated from each other;

an isolator insulating and driving control electrodes of said power semiconductor elements; and

wherein said plurality of power semiconductor elements are each connected to at least two different device terminals in order to provide connectability to said semiconductor device.

16. (Previously Presented) A semiconductor device according to claim 15, wherein said plurality of power semiconductor elements drive an ignition coil.

17. (Previously Presented) A semiconductor device according to claim 15, wherein said plurality of power semiconductor elements drive a fuel injection valve.

18. (Previously Presented) A semiconductor device according to claim 15, wherein said plurality of power semiconductor elements have an input control circuit supplying a control signal of a specific control pattern to said control electrodes of said plurality of power semiconductor elements on the base of input signals.